



## BDB10X Material Safety Data Sheet

<b>Material Content Declaration</b>					
Material name	Substance name e.g. Copper (Cu)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
<b>Lead Wire 19.87%</b>	Copper (Cu)	7440-50-8	101.9785	99.9789	901,905.9
	Phosphorus (P)	7723-14-0	0.0010	0.0010	8.8
	Arsenic (As)	7440-38-2	0.0010	0.0010	8.8
	Tin (Sn)	7440-31-5	0.0010	0.0010	8.8
	Oxygen (O)	7782-44-7	0.0005	0.0005	4.4
	Sulfur (S)	7704-34-9	0.0122	0.0120	107.9
	Iron (Fe)	7439-89-6	0.0007	0.0007	6.2
	Nickel (Ni)	7440-02-0	0.0003	0.0003	2.7
	Bismuth (Bi)	7440-69-9	0.0020	0.0020	17.7
	Antimony (Sb)	1309-64-4	0.0020	0.0020	17.7
	Lead (Pb)	7439-92-1	0.0005	0.0005	4.4
	Zinc (Zn)	7440-66-6	0.0003	0.0003	2.7
	<b>Total</b>		<b>102.00</b>		
<b>Solder Wafer 0.86%</b>	Lead (Pb)	7439-92-1	4.06	92.48	3,590.7
	Tin (Sn)	7440-31-5	0.22	5.01	194.6
	Silver (Ag)	7440-22-4	0.11	2.51	97.3
	<b>Total</b>		<b>4.39</b>		
<b>Chip 0.93%</b>	Silicon (Si)	7440-21-3	4.58	95.40	4,049.9
	Lead (Pb)	7439-92-1	0.22	4.60	195.3
	<b>Total</b>		<b>4.80</b>		
<b>Molding 78.15%</b>	Epoxy	38891-59-7	401.25	100.00	354,868.7
	<b>Total</b>		<b>401.25</b>		
<b>Plating 0.19%</b>	Tin (Sn)	7440-31-5	0.94	100.00	831.3
	<b>Total</b>		<b>0.94</b>		
	<b>Total mass (mg)</b>		<b>113.07</b>		